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Commissioner for Patents
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Signature

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Our File No.: 9281/3898

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

OSAMU, Sakai *et al.*

Serial No. 09/748,530

Filing Date: December 22, 2000

For: SUBSTRATE HAVING REPAIRED
METALLIC PATTERN AND
METHOD AND DEVICE FOR
REPAIRING METALLIC PATTERN
ON SUBSTRATE

Examiner: Zidia T. Pittman

Group Art Unit No.: 1725

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This reply is in response to the Final Office Action dated July 31, 2002. Please reconsider the rejection in view of the remarks presented below.

Please amend the application as follows:

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DEC 03 2002

TC 1700